Applicable standard				
Rating	Operating Temperature Range	1 -40 to +105℃(Note1)	Storage Temperature Range	-10 °C to +60°C (Note3)
	Operating Humidity Range	20% to 80% (Note2)	Storage Humidity Range	40% to 70% (Note3)
	Applicable Connector	DF65-4S-1.7C	Current	AWG 24 : 4.0A
	Voltage	50 V AC/DC		

Specifications

Item	Test method	Requirements	QT	AT
Construction				
General Examination	Visually and by measuring instrument.	According to drawing.	X	X
Marking	Confirmed visually.		X	X
Electric Characteristics				
Contact Resistance Millivolt Level Method	20mV MAX, 1mA (DC or 1000Hz).	10 mΩ MAX.	X	—
Insulation Resistance	100 V DC.	100 MΩ MIN.	X	—
Voltage Proof	500 V AC for 1 min.	No flashover or breakdown.	X	—
Mechanical Characteristics				
Mechanical Operation	30 times insertion and extraction.	1.Contact resistance: 20 mΩ MAX. 2.No damage, crack or looseness of parts.	X	—
1 Contact Insertion and Extraction Forces	It takes out and inserts with a conformity connector.	1.Insertion Force : 22N MAX. 2.Extraction Force: 2.9N MIN.	X	—
Vibration	Frequency 10 to 55 Hz, single amplitude 0.75 mm, at 10 cycles for 3 direction.	1.No electrical discontinuity of 1 μs. 2.No damage, crack or looseness of parts.	X	—
Shock	Acceleration 490 m/s^2 duration of pulse 11 ms at 3 times for 3 directions.		X	—
Environmental Characteristics				
Damp Heat (Steady State)	Exposed at 40 ± 2℃ , humidity 90 to 95 %, 96 h. (After leaving the room temperature for 1 to 2h.)	1.Contact resistance: 20 mΩ MAX. 2.Insulation resistance: 100 MΩ MIN. 3.No damage, crack or looseness of parts.	X	—
Rapid Change Of Temperature	1 Temperature -55℃→ +105℃ Time 30min→ 30min Under 5 Cycles. (The transferring time of the tank is 2 to 3 MIN) (After leaving the room temperature for 1 to 2h.)	1.Contact resistance: 20 mΩ MAX. 2.Insulation resistance: 100 MΩ MIN. 3.No damage, crack or looseness of parts.	X	—
Resistance To Soldering Heat	1) Reflow Soldering Number of reflow cycles : 2 cycles MAX. Duration above 220 ℃, 60 sec. MAX. Peak temperature: 250℃ 10 sec. MAX. Pre-heat temperature :150 to 180 ℃ Pre-heat time : 90 to 120 sec. 2) Manual soldering Soldering iron temperature :350±10℃, Soldering time : 3sec. No strength on contact.	No deformation of case of excessive looseness of the terminals.	X	—
Solderability	Soldering temperature : 245°C Duration of immersion :soldering, for 5 sec.	New uniform coating of solder shall cover minimum of 95 % of the surface Being immersed.	X	—

Remarks
Note 1: Include the temperature rising by current.
Note 2:No condensing
Note 3:Apply to the condition of long term storage for unused products before pcb on board, after pcb board , operating temperature and humidity range is applied for interim storage during transportation.

	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
1	3	DIS-H-00000292	YK.YAMAGUCHI	HK.UMEHARA	15.03.27

APPROVED	KI.AKIYAMA	14.01.15
CHECKED	OM.MIYAMOTO	14.01.15
DESIGNED	TT.OHSAKO	14.01.14
DRAWN	TT.OHSAKO	14.01.14

Unless otherwise specified, refer to IEC 60512.

Note QT:Qualification Test AT:Assurance Test X:Applicable Test

DRAWING NO. ELC4-351454-01

HRS	SPECIFICATION SHEET	PART NO.	DF65-4P-1.7V(21)	
	HIROSE ELECTRIC CO., LTD.	CODE NO.	CL666-6006-0-21	1 1/1

FORM HD0011-2-1